

Product Name: TBD62004APG

Package Name: DIP16

1. Thermal tests

Test Item	Test Condition	Failure Size / Sample Size
Resistance to Soldering Heat for Packages	Solder temperature : 260 deg.C Max, Immersion time : 10s 1 time	0 / 32
Temperature Cycling	-65deg.C (20min) to 25deg.C to 150deg.C (20min) to 25deg.C 500 cycles	0 / 32
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-	-	-

2. Mechanical tests

Test Item	Test Condition	Failure Size / Sample Size
Solderability	Solder temperature : 245deg.C for Solder type Sn-3Ag-0.5Cu Solder immersion time : 5s , Flux type : non-active flux , 1 time	0 / 22
Lead Integrity (Tension)	Tension : according to relevant specification Maintain the specified tension for 30s	0 / 22
Lead Integrity (Bend)	Force : according to relevant specification Bend from -15deg. to 15deg. to 0deg. 1 time	0 / 22
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-	-	-

3. Life tests

Test Item	Test Condition	Failure Size / Sample Size
High Temperature Operating Life	Max operating temperature, Max operating voltage , 1000h	0 / 32
High Temperature Storage Life	Max storage temperature , 1000h	0 / 32
High Temperature High Humidity Bias	Ta=85deg.C, RH=85%, Max operating voltage , 1000h	0 / 32
Autoclave	Ta=121deg.C, RH=100%, 203kPa , 96h	0 / 32
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For detailed reliability test information, such as test conditions and criteria, please contact your Toshiba sales representative.

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1.Flow

Number: Only once

Solder temperature : 260 deg.C maximum

Soldering time : Within 10 seconds

Preheat : Wave solder 25 to 140 deg.C 80 seconds or more / Solder dip 145 deg.C 15 seconds or more

Preheating conditions are based on the surface temperature of the PWB by the solder mounting side.

(When the PWB surface by the device side is preheated, its condition should not exceed the maximum storage temperature of a device.)

If the double-wave method is used, keep the total dwell time for a first bath and a second bath within 10 seconds.

2.Others

We urge you to verify well before mounting to assure enough solder joint strength.

Always solder the Product in accordance with the heat-resistance mounting conditions set forth above. In the event the Product is soldered otherwise, the applicable product warranty, if any, is void.

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